Claims

1. A method for applying a plurality of solder balls to a substrate comprising the steps of:

   placing a plurality of solder balls in a template of a solder ball mounting module, the template having an array of recesses, the step comprises:

   providing a supply of solder balls in a first retention zone; and

   rotating said module so as to move said solder balls from the first retention zone across the template, such that said solder balls are deposited in the recesses of the template as a result of the movement of solder balls across the template;ejecting said solder balls from the module using an ejector pin corresponding to each recess; and receiving said solder balls from the module by the substrate.

2. The method according to claim 1 further including the step of rotating the module to a third position and bring the substrate proximate to the template prior to the ejecting step.

3. The method according to claim 1 or 2 whereby the placing step further includes rotating the module from a first position to a second position so as to cause the solder balls to move across the template.

4. The method according to claim 3 further including the step of rotating the module from the second position to the first position so as to move the solder balls back across the template.

5. The method according to claim 3 or 4 further including the step of moving a wiping blade contiguously across a surface of said template, and so wiping the solder balls across the template so as to bias the solder balls into the respective recesses.